



VACULLOY®

- Good wetting, high fluidity.
- Reduced product usage.
- Low fillets.
- Bright joints – easy inspection.

DESCRIPTION

VACULLOY® is manufactured using high purity raw materials and the alloy is conditioned using Alpha's VACULLOY® viscosity and dross lowering treatment. This results in a pure low dross high fluidity solder alloy, which is free of cast in impurities and included oxides.

FEATURES & BENEFITS

VACULLOY® treated prior to casting: this removes finely divided suspended oxides that are found in all virgin raw materials, this increases the fluidity and hence soldering defects.

- The removal of the finely divided oxide reduces drossing rate, the wave stays cleaner, longer.
- Has a proved track record, no need to take chances.

APPLICATIONS

VACULLOY® is the ideal companion product for all wave soldering systems. VACULLOY® is ideal for the following types of applications:

- High volume wave soldering processes
- Applications requiring dual wave and chip wave systems
- Boards that are densely populated

AVAILABILITY

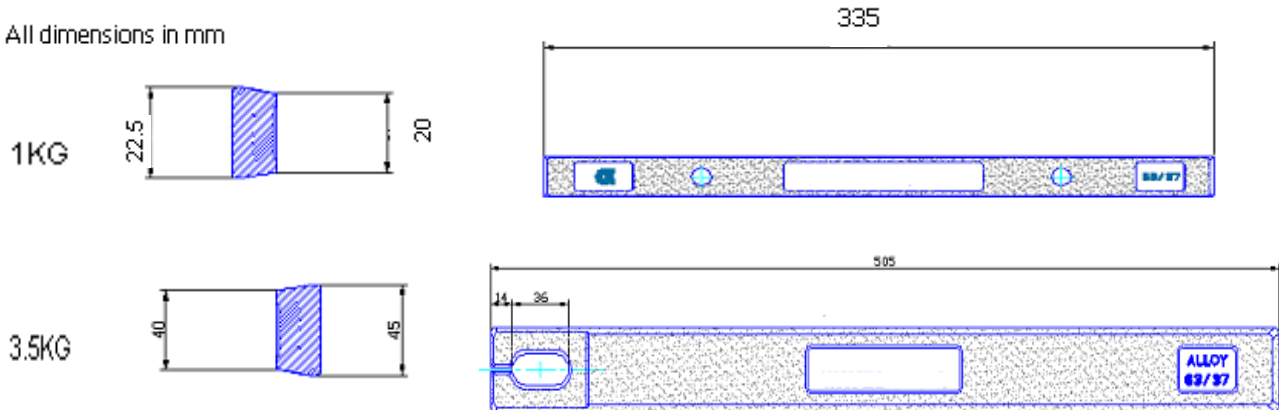
VACULLOY® is available in 3.5Kg feeder bars, 1Kg bars and solder chunks for first fill of solder baths.

HEALTH & SAFETY

Please refer to MSDS for advise on proper handling and safety instructions.

DIMENSIONS OF BARS

All dimensions in mm



TECHNICAL SPECIFICATION

The following indicates the Alloy and impurity limits for VACULOY[®] in relation to J-STD-006A, ISO9453 and JIS Z3282.

ELEMENT	VACULOY [®]	ISO 9453 Alloy 1 ¹	J-STD-006A Sn63Pb37B ²	JIS Z3282A H63A ³
Sn	62.5-63.5	62.5-63.5	62.5-63.5	62.5-63.5
Pb	Balance	Balance	Balance	Balance
Sb	0.12 max	0.12 max	0.02 max	0.12 max
Cu	0.05 max	0.05 max	0.08 max	0.05 max
Zn	0.001 max	0.001 max	0.003 max	0.002 max
Fe	0.01 max	0.02 max	0.02 max	0.02 max
As	0.01 max	0.03 max	0.03 max	0.03 max
Ni	0.01 max	Not specified	0.01 max	Not specified
Bi	0.10 max	0.10 max	0.10 max	0.10 max
Cd	0.001 max	0.002 max	0.002 max	0.002 max
Ag	0.10 max	Not specified	0.10 max	Not specified
Al	0.001 max	0.001 max	0.005 max	0.002 max
In	0.05 max	Not specified	0.10 max	Not specified

All figures are %

1. ISO 9453: 1990

Soft Soldering Alloys - chemical composition and form. ISO - International Standards Organisation, a network of national standards institutes working in partnership.

2. J-STD-006A: May 2001

Requirements for Electronic Grade Solder alloys and non-fluxed solders. Joint Industry Standard between IPC and Electronic Industries Alliance (US Based). IPC formed in 1957 as an Institute of Printed Circuits, J-STD-006A supercedes IPC-SF-818.

3. JIS Z3282:1999

Soft solders chemical composition and forms. JIS - Japanese Industrial Standard.



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